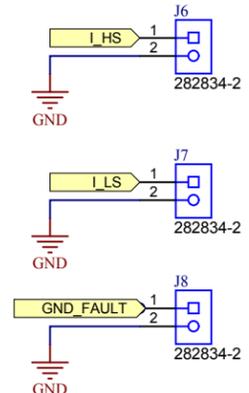
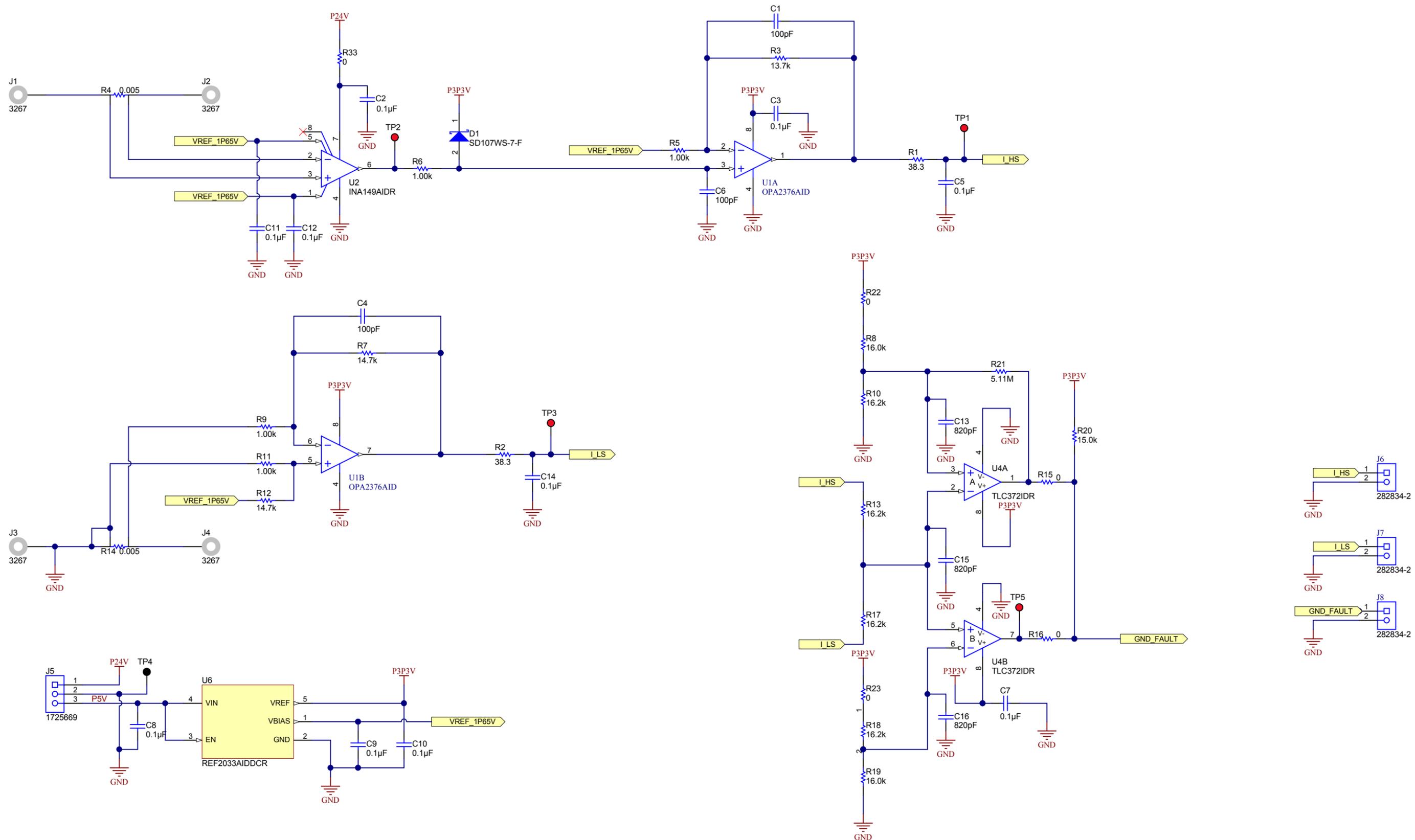


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Orderable: N/A	Designed for: Public Release	Mod. Date: 6/11/2015
TID #:	Project Title: Ground Fault Protection for 110Vac Powered Drives	
Number: TIDA-00439	Rev: E2	Sheet Title: Block Diagram
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By: Pawan N	File: Sh01_CoverSheet.SchDoc	Size: B
Engineer: Pawan N	Contact: http://www.ti.com/support	



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Orderable: N/A	Designed for: Public Release	Mod. Date: 6/11/2015
TID #:	Project Title: Ground Fault Protection for 110Vac Powered Drives	
Number: TIDA-00439	Rev: E2	Sheet Title: Sensing and Signal Conditioning
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By: Pawan N	File: Sh02_Current_sense.SchDoc	Size: B
Engineer: Pawan N	Contact: http://www.ti.com/support	© Texas Instruments 2015



H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

FID1 FID2 FID3 FID4 FID5 FID6

PCB Number: TIDA-00439
PCB Rev: E2

PCB
LOGO
Texas Instruments

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: N/A	Designed for: Public Release	Mod. Date: 6/11/2015	 http://www.ti.com © Texas Instruments 2015
TID #:	Project Title: Ground Fault Protection for 110Vac Powered Drives		
Number: TIDA-00439	Rev: E2	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By: Pawan N	File: Sh03_TID_Hardware.SchDoc	Size: B	
Engineer: Pawan N	Contact: http://www.ti.com/support		

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